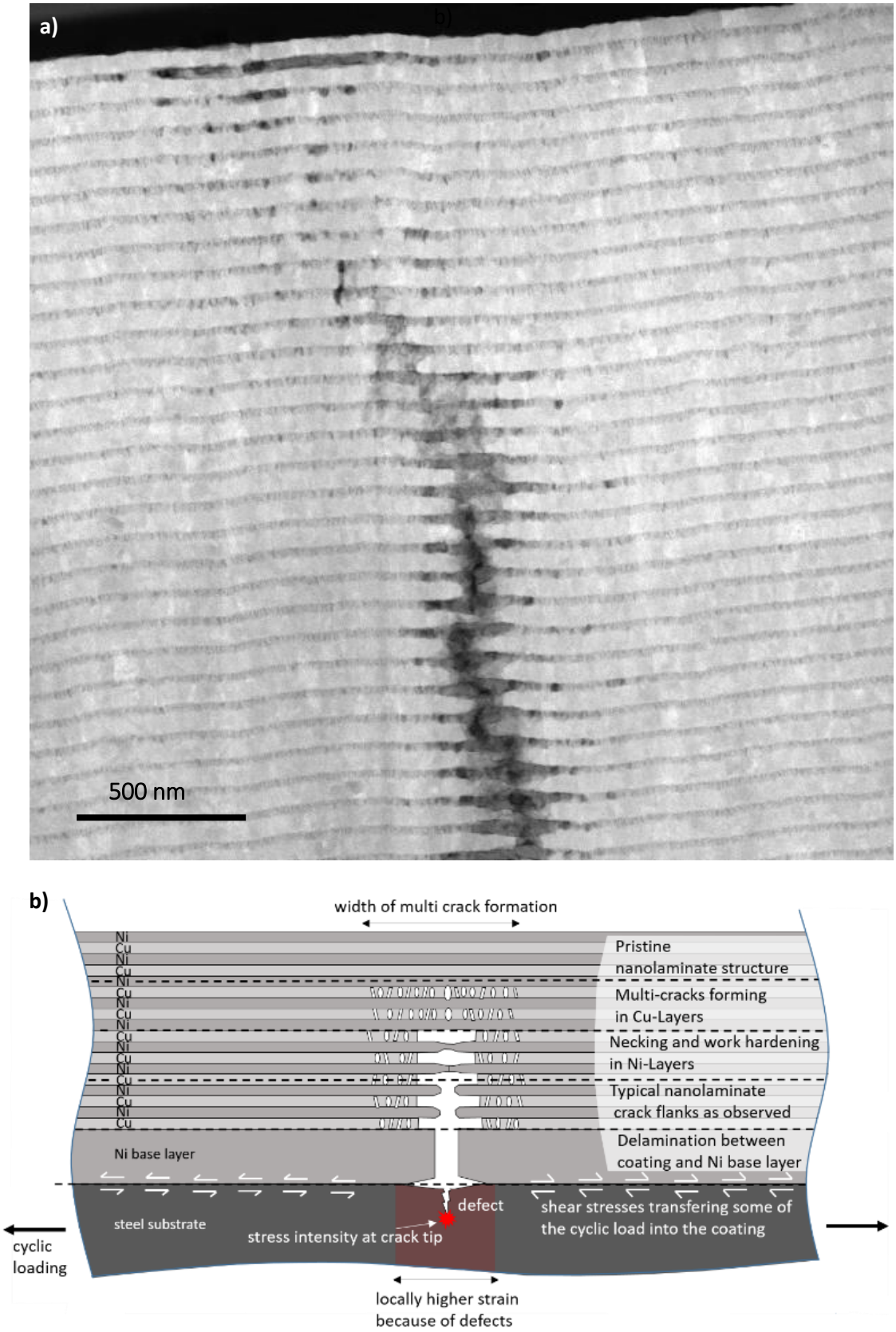

Figure 1. a) HAADF TEM image of the crack tip closure in the top part of the TEM-lamella with multi-cracks forming in the Cu-layers and crack bridging of the Ni-layers; b) schematic crack propagation [5]